

Chanhee Lee

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RESEARCH INTERESTS

- Compute Express Link (CXL), Software Platforms, and On-device Large Language Models (LLMs)

PROFESSIONAL EXPERIENCE

- **University of Central Florida**, Orlando, FL, United States
Postdoctoral Researcher, Department of Computer Science Dec. 2024 - Current
 - Leading memory-saving methods for LLMs in CXL disaggregated memory (submitted to ISCA'26).
 - Research fault-tolerant Non-Volatile Memory (NVM) for transaction-based applications.
- **Arizona State University**, Tempe, AZ, United States
Visiting Scholar (Voluntary), School of Computing and Augmented Intelligence Jan. 2024 - Dec. 2024
 - Led on-device LLM personalization projects with knowledge graphs (published to EMSOFT'24/WWW'25).
 - Developed the Rust version of the core engine of a distributed software framework named [Lingua Franca](#).
- **Samsung Electronics Inc.**, Seoul, Republic of Korea
Staff Engineer/Best Reviewer, Platform Team Aug. 2014 - Dec. 2024
 - Led a RESTful graph database API development and ported it to Android for edge AI.
 - Developed an AI framework for remote inferences between Android and Internet of Things (IoT) devices.
 - Led a flash file system (SmartFS) development for Samsung production boards.
 - Developed an audio manager and APIs for handling audio streams with Samsung ARTIK boards.
 - Led a device-to-device communication framework development with five junior software engineers.

EDUCATION

- **Ph.D., Seoul National University**, Republic of Korea Aug. 2014
 Electrical Engineering and Computer Science
- **MS, Korea Advanced Institute of Science and Technology (KAIST)**, Republic of Korea Feb. 2009
 Computer Science
- **BS, Korea Advanced Institute of Science and Technology (KAIST)**, Republic of Korea Feb. 2007
 Computer Science

SKILLS

- AI Inference Optimization, Performance Analysis, Software Architecture, Rust/Java/C/C++/Python

PUBLICATIONS ([Google Scholar](#))

Peer-reviewed Conference Papers

- Published eight papers as a main/co-author in top-tier venues (EMSOFT/WWW).

Journal Articles

- Published two papers as a main/co-author in Springer/ACM journal (JSPS/TECS)

AWARDS AND HONOUR

- **Samsung Scholarship** for Ph.D. students Mar. 2013 - Feb. 2014
 Samsung Electronics Inc.

INVITED TALK

- **Department of Electrical Engineering, Hanyang University**, South Korea Jun. 2023
 “Remote inference with IoT devices.”

ACADEMIC SERVICES AND MEMBERSHIP

- Secondary reviewer of top-tier venues (ISCA, ASPLOS, HPCA, PPoPP, LCTES) in 2025
- Professional Member of the Association for Computing Machinery (ACM) Apr. 2024 - Current